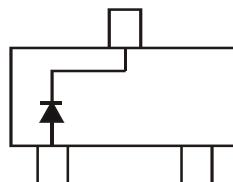


Product Summary (@ T_A = +25°C)

V _{RRM} (V)	I _o (mA)	V _F Max (V)	I _R Max (nA)
40	200	1	200

Description

The BAS40WQ is a 200mA surface mount Schottky Barrier Diode in the SOT323 package. It offers low forward voltage drop and fast switching capabilities, was designed with PN Junction Guard Ring for Transient and ESD Protection, and possesses a totally lead-free finish and RoHS compliant, "Green" device.



BAS40WQ

Mechanical Data

- Case: SOT323
- Case Material: Molded Plastic, "Green" Molding Compound, Note 4. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Solderable per MIL-STD-202, Method 208 (e3)
- Lead-Free Plating (Matte Tin Finish annealed over Alloy 42 Lead-Frame).
- Polarity: See Diagrams Below
- Weight: 0.006 grams (Approximate)



Top View

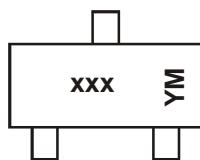
Ordering Information (Notes 4 & 5)

Part Number	Case	Packaging
BAS40WQ-7-F	SOT323	3000/Tape & Reel
BAS40WQ-13-F	SOT323	10000/Tape & Reel

Notes:

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
4. Products manufactured with Date Code V9 (week 33, 2008) and newer are built with Green Molding Compound. Products manufactured prior to Date Code V9 are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants.
5. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

Marking Information



XXX = Product Type Marking Code
K43 = BAS40WQ

YM = Date Code Marking
Y = Year (ex: G = 2019)
M = Month (ex: 9 = September)

Date Code Key

Year	2019	2020	2021	2022	2023	2024	2025	2026	2027	2028	2029	2030	2031	2032	2033	2034
Code	G	H	I	J	K	L	M	N	O	P	R	S	T	U	V	W

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Maximum Ratings (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V_{RRM}		
Working Peak Reverse Voltage	V_{RWM}	40	V
DC Blocking Voltage	V_R		
RMS Reverse Voltage	$V_{R(\text{RMS})}$	28	V
Forward Continuous Current (Note 6)	I_{FM}	200	mA
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-wave Superimposed on Rated Load	I_{FSM}	600	mA

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 6)	P_D	330	mW
Thermal Resistance Junction to Ambient Air (Note 6)	$R_{\theta JA}$	330	°C/W
Operating Temperature Range	T_J	-55 to +125	°C
Storage Temperature Range	T_{STG}	-55 to +150	°C

Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Min	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 7)	$V_{(BR)R}$	40	—	V	$I_R = 10\mu\text{A}$
Forward Voltage	V_F	—	380 1000	mV mV	$I_F = 1.0\text{mA}$, $t_p < 300\mu\text{s}$ $I_F = 40\text{mA}$, $t_p < 300\mu\text{s}$
Leakage Current (Note 7)	I_R	—	200	nA	$V_R = 30\text{V}$
Total Capacitance	C_T	—	5.0	pF	$V_R = 0$, $f = 1.0\text{MHz}$
Reverse Recovery Time	t_{rr}	—	5.0	ns	$I_F = I_R = 10\text{mA}$, $I_{rr} = 0.1 \times I_R$, $R_L = 100\Omega$

Notes: 6. Device mounted on FR4 PC board with recommended pad layout, per <http://www.diodes.com>
 7. Short duration pulse test used to minimize self-heating effect.

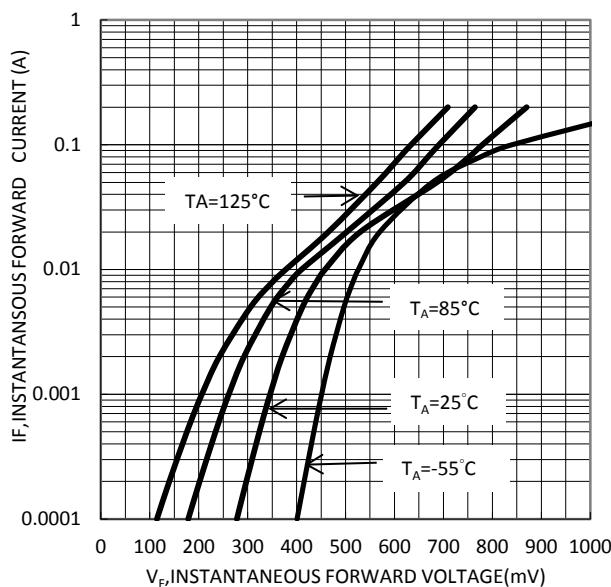


Fig.1 Typical Forward Characteristics

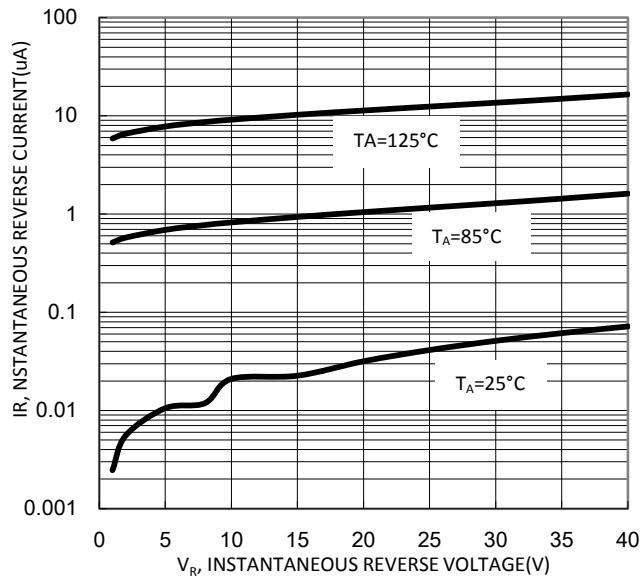


Fig.2 Typical Reverse Characteristics

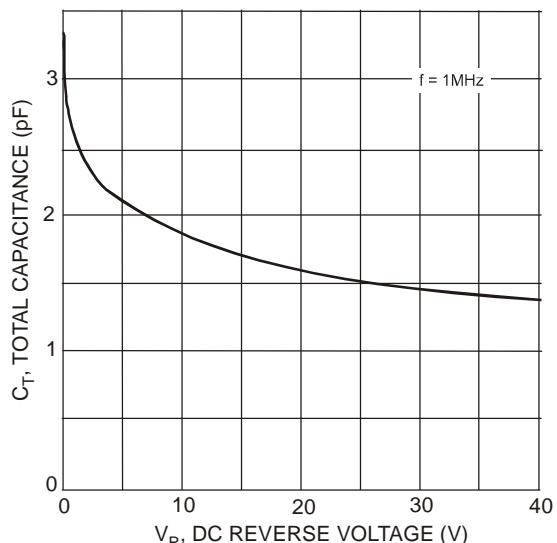


Fig. 3 Total Capacitance vs. Reverse Voltage

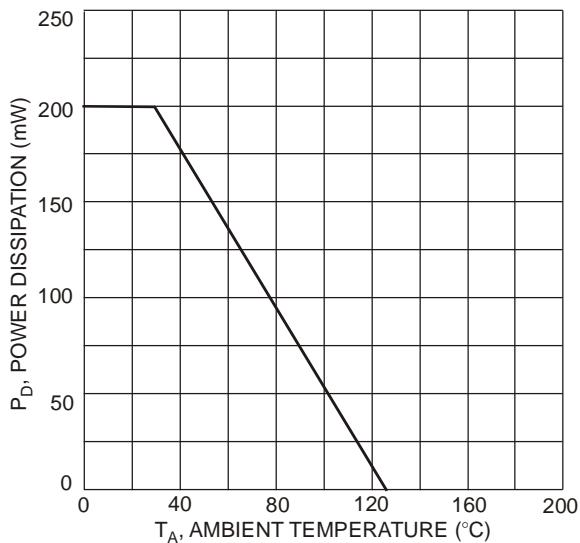
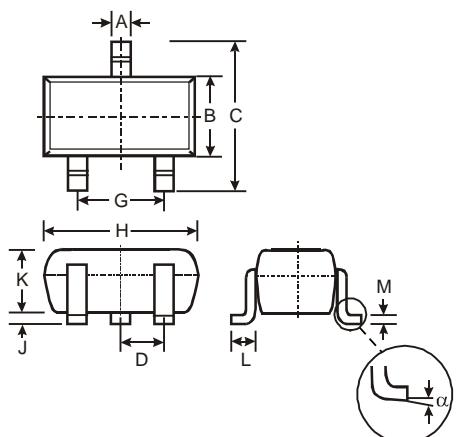


Fig. 4 Power Derating Curve, Total Package

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

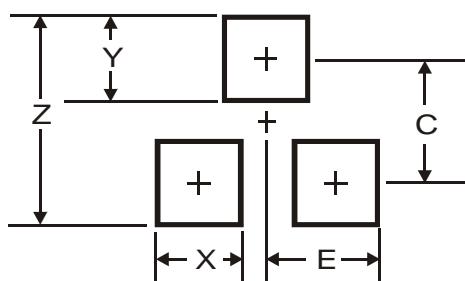


SOT323			
Dim	Min	Max	Typ
A	0.25	0.40	0.30
B	1.15	1.35	1.30
C	2.00	2.20	2.10
D	-	-	0.65
G	1.20	1.40	1.30
H	1.80	2.20	2.15
J	0.0	0.10	0.05
K	0.90	1.00	1.00
L	0.25	0.40	0.30
M	0.10	0.18	0.11
α	0°	8°	-

All Dimensions in mm

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.



Dimensions	Value (in mm)
Z	2.8
X	0.7
Y	0.9
C	1.9
E	1.0

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